

L Number	Hits	Search Text	DB	Time stamp
-	1343	438/106.ccls.	USPAT; US-PGPUB	2003/10/15 11:38
-	189	substrate with (cut same broken)	USPAT; US-PGPUB	2003/10/15 12:18
-	167	(substrate with (cut same broken)) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 11:51
-	2	((substrate with (cut same broken)) not (@ad>20020114 or @rlad>20020114)) and 438/106.ccls.	USPAT; US-PGPUB	2003/10/15 11:51
-	861	substrate with (cut and broken)	USPAT; US-PGPUB	2003/10/15 11:53
-	5	438/106.ccls. and (substrate with (cut and broken))	USPAT; US-PGPUB	2003/10/15 11:52
-	4	(438/106.ccls. and (substrate with (cut and broken))) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 11:53
-	1767	edge with (cut and broken)	USPAT; US-PGPUB	2003/10/15 11:53
-	4	438/106.ccls. and (edge with (cut and broken))	USPAT; US-PGPUB	2003/10/15 11:53
-	3	(438/106.ccls. and (edge with (cut and broken))) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 11:54
-	19853	substrate with cut	USPAT; US-PGPUB	2003/10/15 12:02
-	119	438/106.ccls. and (substrate with cut )	USPAT; US-PGPUB	2003/10/15 11:56
-	89	(438/106.ccls. and (substrate with cut )) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 11:56
-	5852	substrate with broken	USPAT; US-PGPUB	2003/10/15 12:02
-	25	438/106.ccls. and (substrate with broken)	USPAT; US-PGPUB	2003/10/15 12:02
-	18	(438/106.ccls. and (substrate with broken)) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 12:02
-	0	substrate with ("cut portion" and "broken portion")	USPAT; US-PGPUB	2003/10/15 12:11
-	0	substrate same ("cut portion" and "broken portion")	USPAT; US-PGPUB	2003/10/15 12:13
-	4	substrate and ("cut portion" and "broken portion")	USPAT; US-PGPUB	2003/10/15 12:13
-	3	(substrate and ("cut portion" and "broken portion")) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 12:15
-	4	("6573157") or ("6319749") or ("6010384") or ("6281032")).PN. or (2001/0005599).CCLS.	USPAT; US-PGPUB	2003/10/15 12:16
-	23164	substrate and cut and broken	USPAT; US-PGPUB	2003/10/15 12:19
-	443343	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2003/10/15 12:19
-	1001134	semiconductor or "integrated circuit"	EPO; JPO; DERWENT	2003/10/15 12:19
-	0	(substrate and cut and broken) and (semiconductor or "integrated circuit")	EPO; JPO; DERWENT	2003/10/15 12:19
-	233	substrate and cut and broken	EPO; JPO; DERWENT	2003/10/15 12:19
-	59	(semiconductor or "integrated circuit") and (substrate and cut and broken)	EPO; JPO; DERWENT	2003/10/15 15:16
-	3	scribed and etch\$3 and mill\$3 and punched and sheared	USPAT; US-PGPUB	2003/10/15 15:17
-	217460	@ad>20020114 or @rlad>20020114	USPAT; US-PGPUB	2003/10/15 15:17
-	2	(scribed and etch\$3 and mill\$3 and punched and sheared) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 15:17
-	0	substrate with (scribed and etch\$3 and mill\$3 and punched and sheared)	USPAT; US-PGPUB	2003/10/15 15:18

-	0	substrate with (scribed and etch\$3 and mill\$3 and punch\$3 and shear\$3)	USPAT; US-PGPUB	2003/10/15 15:19
-	0	substrate with (scribed and etch and mill and punch and shear)	USPAT; US-PGPUB	2003/10/15 15:24
-	888	substrate with cut with etch\$3	USPAT; US-PGPUB	2003/10/15 15:28
-	781	(substrate with cut with etch\$3) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 15:24
-	70453	438/\$.ccls.	USPAT; US-PGPUB	2003/10/15 15:25
-	204	((substrate with cut with etch\$3) not (@ad>20020114 or @rlad>20020114)) and 438/\$.ccls.	USPAT; US-PGPUB	2003/10/15 15:25
-	120	substrate with cut with mill\$3	USPAT; US-PGPUB	2003/10/15 15:28
-	7	438/\$.ccls. and (substrate with cut with mill\$3)	USPAT; US-PGPUB	2003/10/15 15:28
-	7	(438/\$.ccls. and (substrate with cut with mill\$3)) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 15:40
-	1397	broken with punch\$3	USPAT; US-PGPUB	2003/10/15 15:40
-	9	substrate with broken with punch\$3	USPAT; US-PGPUB	2003/10/15 15:41
-	4	438/\$.ccls. and (substrate with broken with punch\$3)	USPAT; US-PGPUB	2003/10/15 15:40
-	2	(438/\$.ccls. and (substrate with broken with punch\$3)) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/15 15:40
-	239	substrate with cut with punch\$3	USPAT; US-PGPUB	2003/10/15 15:42
-	15	438/\$.ccls. and (substrate with cut with punch\$3)	USPAT; US-PGPUB	2003/10/15 15:41
-	14	(438/\$.ccls. and (substrate with cut with punch\$3)) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/16 10:42
-	28	substrate with broken with shear\$3	USPAT; US-PGPUB	2003/10/15 15:42
-	6	438/\$.ccls. and (substrate with broken with shear\$3)	USPAT; US-PGPUB	2003/10/16 11:10
-	2	(438/\$.ccls. and (substrate with broken with punch\$3)) not (@ad>20020114 or @rlad>20020114)	USPAT; US-PGPUB	2003/10/16 10:45
-	4	("5420460") or ("5598096") or ("5608262") or ("5719440")).PN.	USPAT; US-PGPUB	2003/10/16 12:40
-	1	("20010024860").PN.	USPAT; US-PGPUB	2003/10/16 12:40